CLAIMS

1. A conductive adhesive comprising the following components (A) to (C), the conductive adhesive being liquid at 25°C:

component (A): an alicyclic epoxy resin;

component (B): a boron-based thermal cationic initiator; and

component (C): a conductive filler,

wherein the component (C) contains a conductive filler (C-1) having a 50% average particle diameter of 3 μm or more and a conductive filler (C-2) having a 50% average particle diameter of less than 3 μm and a ratio of a mass of the component (C-1) to a mass of the component (C-2) is 0.01 to 30.

2. The conductive adhesive according to claim 1, wherein the component (B) contains a salt of a quaternary ammonium cation and a borate anion.

3. The conductive adhesive according to claim 1 or 2, wherein the component (B) contains at least either of a salt of a quaternary ammonium cation and a tetrafluoroborate anion or a salt of a quaternary ammonium cation and a tetrakis(pentafluorophenyl)borate anion.

4. The conductive adhesive according to any one of claims 1 to 3, wherein at least one of the component ~~(C)~~ (C-1) or the component (C-2) ~~is a conductive filler having~~ has a surface treated with a lubricant.

5. The conductive adhesive according to any one of claims 1 to 4, wherein the component (A) is an alicyclic epoxy resin having two or more epoxy groups in one molecule.

6. The conductive adhesive according to any one of claims 1 to 5, wherein a tap density of each conductive filler as the component (C) is 0.1 to 100 g/cm^3.

7. The conductive adhesive according to any one of claims 1 to 6, wherein the component (C) has a plurality of shapes.

~~8. The conductive adhesive according to any one of claims 1 to 7, wherein the component (C) contains a conductive filler (C-1) having a 50% average particle diameter of 3 μm or more and a conductive filler (C-2) having a 50% average particle diameter of less than 3 μm and a ratio of a mass of the component (C-1) to a mass of the component (C-2) is 0.01 to 30.~~

8~~9~~. The conductive adhesive according to any one of claims 1 to ~~8~~ 7, wherein the component (B) is contained at 0.1 to 30 parts by mass with respect to 100 parts by mass of the component (A).

9~~10~~. The conductive adhesive according to any one of claims 1 to ~~9~~ 8, wherein the component (B) is contained at 1 to 20 parts by mass with respect to 100 parts by mass of the component (A).

10~~11~~.The conductive adhesive according to any one of claims 1 to ~~10~~ 9, which is used for an adherend containing polycarbonate.

11~~12~~.A cured product of the conductive adhesive set forth in any one of claims 1 to~~11~~ 10.